

## PATENT ASSIGNMENT COVER SHEET

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<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT	
<b>CONVEYING PARTY DATA</b>		
	<b>Name</b>	<b>Execution Date</b>
	MITSunari Sukekawa	03/06/2019
<b>RECEIVING PARTY DATA</b>		
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<b>State/Country:</b>	IDAHO	
<b>Postal Code:</b>	83716	
<b>PROPERTY NUMBERS Total: 1</b>		
	<b>Property Type</b>	<b>Number</b>
	Application Number:	16294782
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<b>SIGNATURE:</b>	/Cheryl A. Thompson/	
<b>DATE SIGNED:</b>	03/06/2019	
<b>Total Attachments: 4</b>		
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## ASSIGNMENT

### PARTIES TO THE ASSIGNMENT:

#### INVENTOR:

Mitsunari Sukekawa  
c/o Micron Memory Japan, Inc.  
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1-2-70, Konan, Minato-ku  
108-0075 Tokyo  
Japan

#### ASSIGNEE:

Micron Technology, Inc.  
MS 1-525  
8000 South Federal Way  
Boise, ID 83716  
United States

### BACKGROUND OF THIS ASSIGNMENT:

Inventor has conceived certain new and useful inventions disclosed in a United States patent application titled Methods of Compensating for Misalignment of Bonded Semiconductor Wafers.

Micron Technology, Inc. (hereinafter referred to as "ASSIGNEE") desires to acquire the entire right, title and interest in said inventions and with respect to any Letters Patent(s) that may be granted with respect to the inventions in both the United States and in all foreign countries.

**THE PARTIES AGREE AS FOLLOWS:**

In consideration of good and valuable consideration, the receipt, sufficiency and adequacy of which is hereby acknowledged, INVENTOR has sold, assigned and transferred, and by these presents does hereby sell, assign and transfer to ASSIGNEE the entire right, title and interest in the above-identified inventions and patent application(s) and to any reissues, renewals, divisions or continuations of the application(s) thereof, and hereby authorizes the Commissioner of Patents and Trademarks to issue such Letters Patent(s) to ASSIGNEE for the sole use of ASSIGNEE, its successors or assigns.

INVENTOR further agrees to execute, at the request and expense of ASSIGNEE, such other formal documents as may be required to fully convey the interest transferred herein and will similarly execute any patent application papers (domestic or foreign) required for the filing of any divisional, continuation, renewal or reissue of the patent application(s) or resulting Letters Patent(s); and will generally do everything necessary or desirable to obtain and enforce proper protection for the inventions assigned hereby.

INVENTOR further assigns to ASSIGNEE the whole right, title and interest in the inventions disclosed in the application(s) throughout all countries foreign to the United States. ASSIGNEE is hereby authorized to apply for patents relating to the inventions in its own name in countries where such procedure is proper; to claim the benefit of the International

Convention; to file and prosecute International Applications relating to the inventions under the Patent Cooperation Treaty; and to file and prosecute applications relating to the inventions under the European Patent Convention. INVENTOR agrees to execute application(s) relating to the inventions in those countries and under those conventions where it is necessary that the same be executed by the inventor, and to execute assignments of such applications and the resulting Letters Patent(s) to ASSIGNEE as well as all other necessary papers in relation to such applications and Letters Patent(s). INVENTOR hereby consents that a copy of this assignment shall be deemed a full legal and formal equivalent of any document which may be required in any country as proof of the right of ASSIGNEE to apply for patent and other form of protection for said inventions and to claim the aforesaid benefit of the right of priority.

To be binding on the heirs, assigns, representatives and successors of the undersigned and extend to the successors, assigns and nominees of the Assignee.

Dated: Mar. 6th. 2019

Signature: Mitsunari Sukekawa  
Mitsunari Sukekawa

On this day before me personally appeared Mitsunari Sukekawa, known or identified to me (or proved to me on the basis of satisfactory evidence) to be the person whose name is subscribed within the Assignment, and acknowledged to me that he/she executed the Assignment in his/her authorized capacity, and that by his/her signature on the Assignment, the person executed the Assignment.

Witness Name (printed): Shoji Eguchi

Witness Signature: Shoji Eguchi

Date: 3/6/2019

Witness Name (printed): Shoko Tomita

Witness Signature: Shoko Tomita

Date: 03-06-2019